

Title (en)
METHOD FOR REFLOW SOLDERING

Title (de)
VERFAHREN ZUM REFLOW-LÖTEN

Title (fr)
PROCEDE DE BRASAGE PAR FUSION

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Application
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Abstract (en)
[origin: WO2005101932A1] The invention relates to a method and device for reflow soldering strip conductors to components and to modules (4), which are attached to a printed circuit board (1) by means of a soldering paste. According to the invention, an absorption material is heated by radiating an electromagnetic wave during which the material absorbs this radiation, and this heating is transferred to the soldering paste for melting a solder contained in the soldering paste. The soldering paste is mixed with the absorption material to form a mixed material (3), and the mixed material is applied to the soldering points of the strip conductors (2).

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